

型号：MT18SD-H-T5

- MicroThin™为带有18 μm载体箔的超薄铜箔。
MicroThin™ is ultra thin foil with 18 μm carrier foil.
- 适用于无芯封装工艺。
Suitable for core-less process

用途/Application

- 半导体封装基板
/Semiconductor Package
- 无芯封装基板
/Core-less substrate

构成/Composition



生产地点/Production Site

- 日本 / Japan

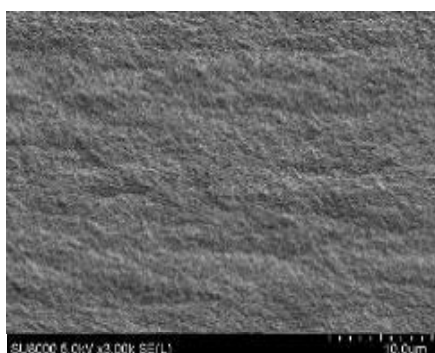
代表性特性数据/Representative data

Model No.	μm	Area weight (g/m ²)	Deposited side Rz (μm)	Tensile Strength (N/mm ²)	Elongation (%)	Peel Strength (kg/cm)@FR- 4
MT18SD-H-T5	5	40	1	-	-	-

※上述列表为代表性数据，非保证数据。

This is representative data, not guaranteed.

处理面/Treated side



剥离面/Releasing side

